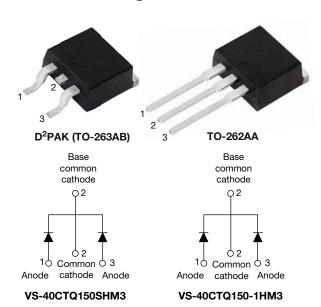
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COMPLIANT

HALOGEN

FREE

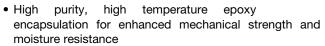
High Performance Schottky Rectifier, 2 x 20 A



PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 20 A					
V_{R}	150 V					
V _F at I _F	0.71 V					
I _{RM}	15 mA at 125 °C					
T _J max.	175 °C					
E _{AS}	1 mJ					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- · Very low forward voltage drop
- 175 °C T_J operation
- Center tap TO-220 package
- High frequency operation



- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Meet JESD 201 class 1 whisker test
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

The VS-40CTQ... center tap Schottky rectifier has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	VALUES	UNITS			
I _{F(AV)}	Rectangular waveform	40	A			
V _{RRM}		150	V			
I _{FSM}	$t_p = 5 \mu s sine$	1500	А			
V _F	20 A _{pk} , T _J = 125 °C (per leg)	0.71	V			
T _J		-55 to +175	°C			

VOLTAGE RATINGS					
PARAMETER	SYMBOL	VS-40CTQ150SHM3 VS-40CTQ150-1HM3	UNITS		
Maximum DC reverse voltage	V _R	150	W		
Maximum working peak reverse voltage	V_{RWM}	130	V		



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ABSOLUTE MAXIMUM RATINGS								
PARAMETER		SYMBOL	TEST CONDI	TEST CONDITIONS		UNITS		
Maximum average forward per leg current, see fig. 5 per device		1	50 % duty ovalo at T ₋ = 140 %	rootangular wayoform	20			
		I _{F(AV)}	50 % duty cycle at T_C = 140 °C, rectangular waveform		40			
Market and a second and a			5 μs sine or 3 μs rect. pulse	Following any rated	1500	Α		
Maximum peak one cycle non-repetitive surge current per leg, see fig. 7		I _{FSM}	10 ms sine or 6 ms rect. pulse	load condition and with rated V _{RRM} applied	250			
Non-repetitive avalanche energy per leg		E _{AS}	$T_J = 25$ °C, $I_{AS} = 1.5$ A, $L = 0.9$ mH		1.0	mJ		
Repetitive avalanche current per	r leg	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical		1.5	Α		

ELECTRICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CO	NDITIONS	VALUES	UNITS		
		20 A	T ₁ = 25 °C	0.93			
Maximum forward voltage drop per leg See fig. 1	V (1)	40 A	1J=25 C	1.16	V		
	V _{FM} ⁽¹⁾	20 A	T 105 00	0.71			
		40 A	T _J = 125 °C	0.85			
Maximum reverse leakage current per leg	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	50	μΑ		
See fig. 2		T _J = 125 °C	V _R = nateu V _R	15	mA		
Maximum junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal ran	ge 100 kHz to 1 MHz), 25 °C	450	pF		
Typical series inductance per leg	L _S	Measured lead to lead 5 mm from package body		8.0	nH		
Maximum voltage rate of change	dV/dt	Rated V _R 10 000					

Note

 $^{^{(1)}\,}$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Maximum junction and storage temperature range	T _J , T _{Stg}		-55 to +175	°C			
Maximum thermal resistance, junction to case per leg	В	DC operation See fig. 4	1.5				
Maximum thermal resistance, junction to case per package	- R _{thJC}	DC operation	0.75	°C/W			
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth and greased	0.5				
Approximate weight			2	g			
Approximate weight			0.07	OZ.			
Marking device		Case style D ² PAK (TO-263AB)	40CTQ	150SH			
ivial king device		Case style TO-262	40CTQ	150-1H			



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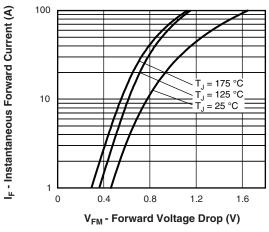


Fig. 1 - Maximum Forward Voltage Drop Characteristics

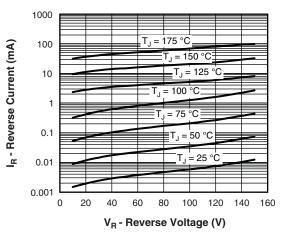


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

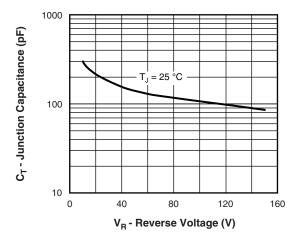


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

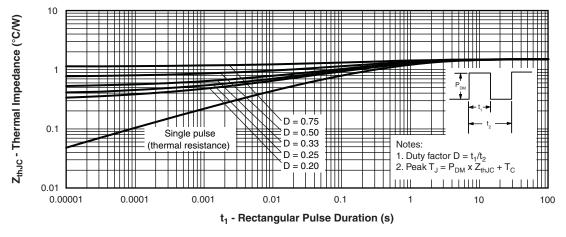


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

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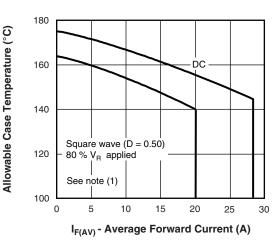


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

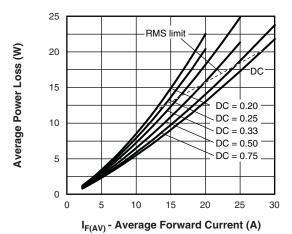


Fig. 6 - Forward Power Loss Characteristics

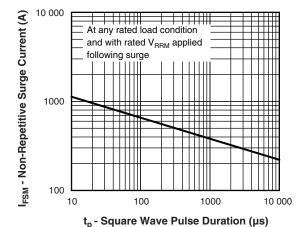


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

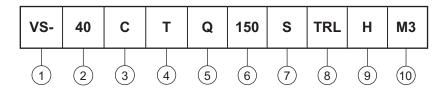
Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6);} \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = 80 \% V_R \text{ applied} \\ \end{array}$

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (40 A)

- Circuit configuration:

C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

6 - Voltage rating (150 = 150 V)

7 - • S = D²PAK

• -1 = TO-262

None = tube (50 pieces)

• TRL = tape and reel (left oriented - for D²PAK only)

• TRR = tape and reel (right oriented - for D²PAK only)

9 - H = AEC-Q101 qualified

| 10 | - M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-40CTQ150SHM3	50	1000	Antistatic plastic tubes			
VS-40CTQ150STRLHM3	800	800	13" diameter reel			
VS-40CTQ150STRRHM3	800	800	13" diameter reel			
VS-40CTQ150-1HM3	50	1000	Antistatic plastic tubes			

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
Diffiersions	TO-262AA	www.vishay.com/doc?96165				
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
	TO-262AA	www.vishay.com/doc?95443				
Packaging information		www.vishay.com/doc?95032				
SPICE model		www.vishay.com/doc?95434				



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	HES	NOTES		SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164

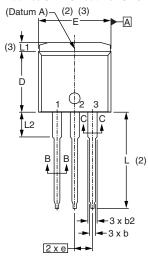


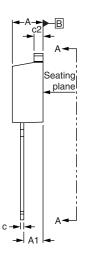
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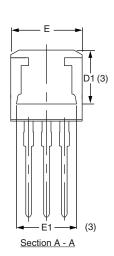
TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262







⊕ 0.010 **M** A**M** B

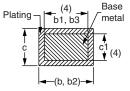
Lead assignments



Diodes 1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

CVMDOL	MILLIM	IETERS	INC	INCHES			
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
Е	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54	BSC	0.10	0 BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.56	3.71	0.140	0.146			

Notes

(4) Dimension b1 and c1 apply to base metal only

Controlling dimension: inches

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

Thermal pad contour optional within dimension E, L1, D1 and E1

Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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